

APFA2507LSURKSYKZGKC

2.5 x 0.7 mm Right Angle SMD Chip LED Lamp



DESCRIPTIONS

- The Hyper Red source color devices are made with AlGaInP on GaAs substrate Light Emitting Diode
- The Super Bright Yellow device is made with AlGaInP (on GaAs substrate) light emitting diode chip
- The Green source color devices are made with InGaN on Sapphire Light Emitting Diode
- · Electrostatic discharge and power surge could damage the LEDs
- · It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs
- · All devices, equipments and machineries must be electrically grounded

FEATURES

- 2.5 x 1.0 x 0.7 mm right angle SMD LED, 0.7 mm thickness
- Low power consumption
- · Wide viewing angle
- · Ideal for backlight and indicator
- Package: 3000 pcs / reel
- Moisture sensitivity level: 3
- Tinned pads for improved solderability
- Halogen-free
- RoHS compliant

APPLICATIONS

- Backlight
- Status indicator
- · Home and smart appliances
- · Wearable and portable devices
- · Healthcare applications

ATTENTION

Observe precautions for handling electrostatic discharge sensitive devices

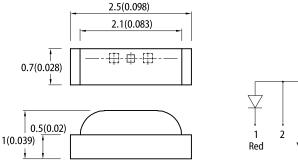


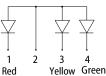
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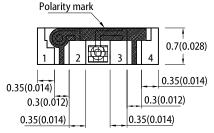
ELECTION GUIDE									
Devit Nevrels on	Emitting Color	1 T	lv (mcd) @ 2mA ^[2]		Viewing Angle [1]				
Part Number	(Material)	Lens Type	Min.	Тур.	Viewing Angle [1] 201/2 - 130° -				
APFA2507LSURKSYKZGKC	Hyper Red (AlGaInP)	Water Clear	20	30	130°				
			*6	*10					
	Super Bright Yellow (AlGaInP)		6	15					
			*6	*15					
	Green (InGaN)		20	60					
			*20	*60					

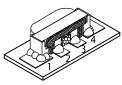
Notes: 1. 01/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value. 2. Luminous intensity / luminous flux: +/-15%. * Luminous intensity value is traceable to CIE127-2007 standards.

PACKAGE DIMENSIONS



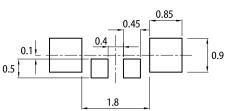






RECOMMENDED SOLDERING PATTERN

(units : mm; tolerance : ± 0.1)



Notes

All dimensions are in millimeters (inches).
Tolerance is ±0.15(0.006") unless otherwise noted.
The specifications, characteristics and technical data described in the datasheet are subject to

The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice. The device has a single mounting surface. The device must be mounted according to the specifications. For right angle SMD LEDs, the solder stencil should be at least 5mil in thickness, to prevent poor solder wetting due to insufficient solder paste.

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ELECTRICAL / OPTICAL CHARACTERISTICS at T_A=25°C

Devenuedan	Question	Emitting Color	Value		Unit
Parameter	Symbol	Emitting Color	Typ. Max.		
Wavelength at Peak Emission $I_F = 2mA$	λ _{peak}	Hyper Red Super Bright Yellow Green	645 590 515	-	nm
Dominant Wavelength I _F = 2mA	λ_{dom} ^[1]	Hyper Red Super Bright Yellow Green	630 590 525	-	nm
Spectral Bandwidth at 50% Φ REL MAX I _F = 2mA			28 20 35	-	nm
Capacitance	с	Hyper Red Super Bright Yellow Green	35 20 45	-	pF
Forward Voltage I _F = 2mA	V _F ^[2]	Hyper Red Super Bright Yellow Green	1.75 1.85 2.65	2.2 2.2 3.1	V
Reverse Current ($V_R = 5V$)	I _R	Hyper Red Super Bright Yellow Green	-	10 10 50	μA
Temperature Coefficient of λ_{peak} I_F = 2mA, -10°C \leq T \leq 85°C	TC_{\lambdapeak}	Hyper Red Super Bright Yellow Green	0.14 0.12 0.05	-	nm/°C
$\label{eq:transformation} \begin{tabular}{l} \mbox{Temperature Coefficient of λ_{dom}} \\ \mbox{F} = 2mA, -10^\circ C \le T \le 85^\circ C \end{tabular} \end{tabular} \begin{tabular}{l} \mbox{TC}_{\lambda dom} \\ \mbox{Green} \end{tabular} \end{tabular} \end{tabular} \end{tabular}$		Super Bright Yellow	0.05 0.07 0.03	-	nm/°C
Temperature Coefficient of $~V_F$ I_F = 2mA, -10°C \leq T \leq 85°C	TCv	Hyper Red Super Bright Yellow Green	-1.9 -1.9 -3	-	mV/°C

Notes:

The dominant wavelength (λd) above is the setup value of the sorting machine. (Tolerance λd: ±1nm.)
Forward voltage: ±0.1V.
Wavelength value is traceable to CIE127-2007 standards.
Excess driving current and / or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

ABSOLUTE MAXIMUM RATINGS at $T_A=25^{\circ}C$

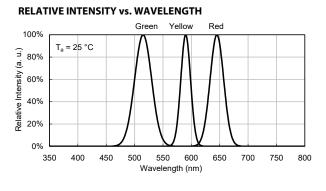
Demonster	Symbol	Value			
Parameter		Hyper Red	Super Bright Yellow	Green	Unit
Power Dissipation	PD	75	75	102.5	mW
Reverse Voltage	V _R	5	5	5	V
Junction Temperature	Tj	115	115	115	°C
Operating Temperature	T _{op}	-40 to +85			°C
Storage Temperature	T _{stg}	-40 to +85			°C
DC Forward Current	l _F	30	30	25	mA
Peak Forward Current	I _{FM} ^[1]	185	175	150	mA
Electrostatic Discharge Threshold (HBM)	-	3000	3000	450	V
Thermal Resistance (Junction / Ambient)	R _{th JA} ^[2]	480	770	490	°C/W
Thermal Resistance (Junction / Solder point)	R _{th JS} ^[2]	350	660	370	°C/W

Notes: 1. 1/10 Duty Cycle, 0.1ms Pulse Width. 2. R_{th. us}, R_{m. us} Results from mounting on PC board FR4 (pad size ≥ 16 mm² per pad). 3. Relative humidity levels maintained between 40% and 60% in production area are recommended to avoid the build-up of static electricity – Ref JEDEC/JESD625-A and JEDEC/J-STD-033.

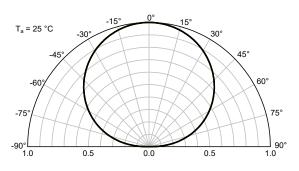
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TECHNICAL DATA



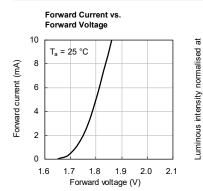
SPATIAL DISTRIBUTION

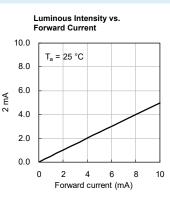


Luminous intensity normalised at

Ta = 25 °C

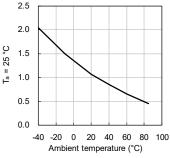
HYPER RED





Forward Current Derating Curve





Forward Current vs. Forward Voltage 10 Luminous intensity normalised at T_a = 25 °C 8 Forward current (mA) 6 4 2 0 2.2 1.8 1.9 2.0 2.1 1.7 Forward voltage (V)

Forward Current vs.

Forward voltage (V)

Forward Voltage

T_a = 25 °C

10

8

6

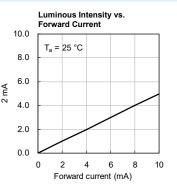
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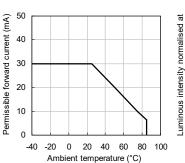
2.3 2.5 2.7 2.9 3.1

Forward current (mA)

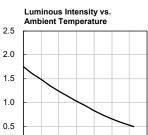


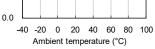
SUPER BRIGHT YELLOW

GREEN

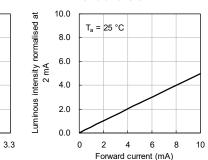


Forward Current Derating Curve

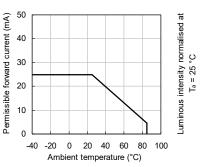




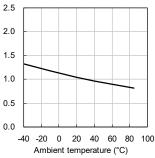




Forward Current Derating Curve



Luminous Intensity vs. Ambient Temperature

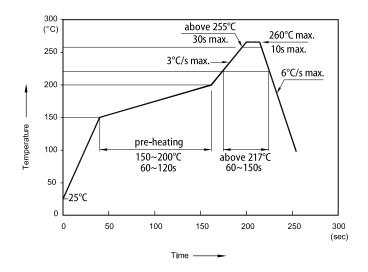


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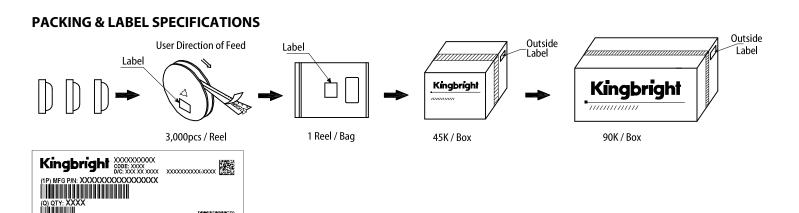
REFLOW SOLDERING PROFILE for LEAD-FREE SMD PROCESS



Notes

(4L) COO: CN

 Don't cause stress to the LEDs while it is exposed to high temperature.
The maximum number of reflow soldering passes is 2 times.
Reflow soldering is recommended. Other soldering methods are not recommended as they might cause damage to the product.



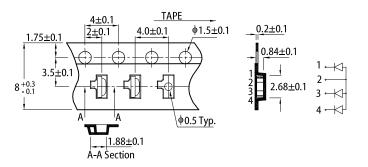
PRECAUTIONARY NOTES

ODE: XXXX

xxx

- 1.
- The information included in this document reflects representative usage scenarios and is intended for technical reference only. The part number, type, and specifications mentioned in this document are subject to future change and improvement without notice. Before production usage customer should refer to the latest datasheet for the updated specifications.
- 3. When using the products referenced in this document, please make sure the product is being operated within the environmental and electrical limits specified in the datasheet. If customer usage exceeds the specified limits, Kingbright will not be responsible for any subsequent issues. The information in this document applies to typical usage in consumer electronics applications. If customer's application has special reliability requirements or have life-threatening
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- 6. All design applications should refer to Kingbright application notes available at https://www.King tionNotes

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REEL DIMENSION (units : mm)

TAPE SPECIFICATIONS (units : mm)

